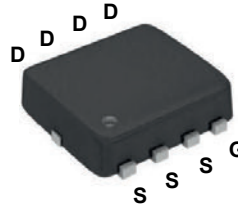
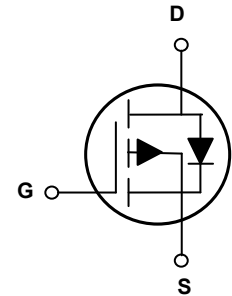


### Main Product Characteristics

$V_{(BR)DSS}$	-60V
$R_{DS(ON)}$	49mΩ (Max.)
$I_D$	-28A



PPAK3x3



Schematic Diagram

### Features and Benefits

- Advanced MOSFET process technology
- Ideal for high efficiency switched mode power supplies
- Low on-resistance with low gate charge
- Fast switching and reverse body recovery



### Description

The GSFN6049 utilizes the latest techniques to achieve high cell density and low on-resistance. These features make this device extremely efficient and reliable for use in high efficiency switch mode power supplies and a wide variety of other applications.

### Absolute Maximum Ratings ( $T_A=25^{\circ}\text{C}$ unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	$V_{DS}$	-60	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Drain Current-Continuous ( $T_C=25^{\circ}\text{C}$ )	$I_D$	-28	A
Drain Current-Continuous ( $T_C=100^{\circ}\text{C}$ )		-16	
Drain Current-Pulsed <sup>1</sup>	$I_{DM}$	-112	A
Single Pulse Avalanche Energy <sup>2</sup>	$E_{AS}$	484	mJ
Single Pulse Avalanche Current <sup>2</sup>	$I_{AS}$	-14	A
Power Dissipation ( $T_C=25^{\circ}\text{C}$ )	$P_D$	40	W
Power Dissipation-Derate above 25°C		0.32	
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	62	°C/W
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	3.13	°C/W
Operating Junction Temperature Range	$T_J$	-55 To +150	°C
Storage Temperature Range	$T_{STG}$	-55 To +150	°C

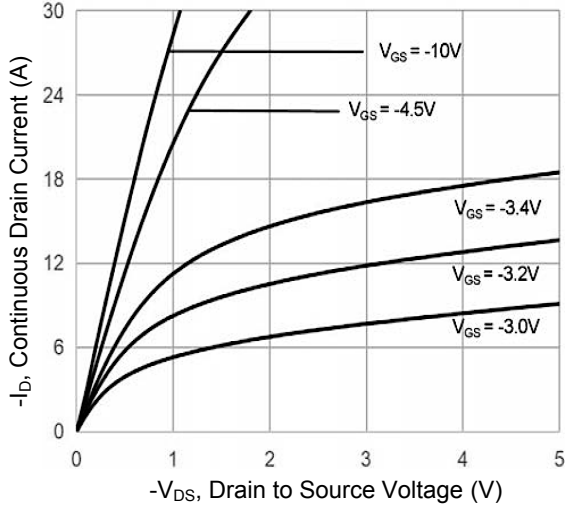
**Electrical Characteristics** ( $T_J=25^{\circ}\text{C}$  unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
<b>On / Off Characteristics</b>						
Drain-to-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS}=0\text{V}, I_D=-250\mu\text{A}$	-60	-	-	V
Drain-to-Source Leakage Current	$I_{DSS}$	$V_{DS}=-60\text{V}, V_{GS}=0\text{V}, T_J=25^{\circ}\text{C}$	-	-	-1.0	$\mu\text{A}$
		$V_{DS}=-60\text{V}, V_{GS}=0\text{V}, T_J=125^{\circ}\text{C}$	-	-2.2	-	
Gate-to-Source Forward Leakage	$I_{GSS}$	$V_{DS}=0\text{V}, V_{GS}=20\text{V}$	-	-	100	nA
		$V_{DS}=0\text{V}, V_{GS}=-20\text{V}$	-	-	-100	
Static Drain-to-Source On-Resistance	$R_{DS(ON)}$	$V_{GS}=-10\text{V}, I_D=-7\text{A}$	-	35	49	m $\Omega$
		$V_{GS}=-4.5\text{V}, I_D=-6\text{A}$	-	43	59	
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=-250\mu\text{A}$	-1.1	-	-2.7	V
<b>Dynamic and Switching Characteristics</b>						
Input Capacitance	$C_{iss}$	$V_{GS}=0\text{V}, V_{DS}=-30\text{V}, f=1\text{MHz}$	-	727	-	$\text{pF}$
Output Capacitance	$C_{oss}$		-	161	-	
Reverse Transfer Capacitance	$C_{rss}$		-	17	-	
Total Gate Charge <sup>3,4</sup>	$Q_g$	$I_D=-10\text{A}, V_{DD}=-30\text{V}, V_{GS}=-10\text{V}$	-	13.4	-	nC
Gate-to-Source Charge <sup>3,4</sup>	$Q_{gs}$		-	3.4	-	
Gate-to-Drain ("Miller") Charge <sup>3,4</sup>	$Q_{gd}$		-	1.9	-	
Turn-On Delay Time <sup>3,4</sup>	$t_{d(on)}$	$V_{DD}=-30\text{V}, V_{GS}=-10\text{V}, R_G=5\Omega, I_D=-10\text{A}$	-	10	-	nS
Rise Time <sup>3,4</sup>	$t_r$		-	6	-	
Turn-Off Delay Time <sup>3,4</sup>	$t_{d(off)}$		-	2	-	
Fall Time <sup>3,4</sup>	$t_f$		-	12	-	
Gate Resistance	$R_g$	$f=1\text{MHz}$	-	2.9	-	$\Omega$
<b>Drain-Source Ratings and Characteristics</b>						
Continuous Source Current (Body Diode)	$I_S$	MOSFET symbol showing the integral reverse p-n junction diode.	-	-	-28	A
Diode Pulse Current	$I_{S,pulse}$		-	-	-112	A
Diode Forward Voltage	$V_{SD}$	$I_S=-5\text{A}, V_{GS}=0\text{V}$	-	-	-1.4	V
Reverse Recovery Time <sup>3</sup>	$t_{rr}$	$I_S=-10\text{A}, V_{GS}=0\text{V}, V_R=-30\text{V}, dI_F/dt=100\text{A/us}$	-	18	-	nS
Reverse Recovery Charge <sup>3</sup>	$Q_{rr}$		-	27	-	nC

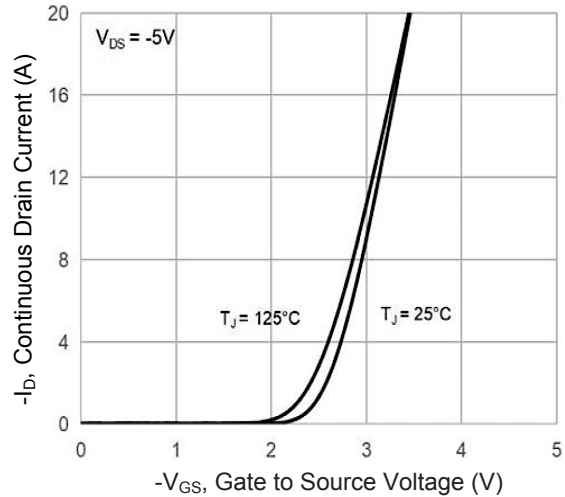
Note:

1. The rated value only refers to the maximum absolute value under  $25^{\circ}\text{C}$  shell temperature in the manual. If the shell temperature is higher than  $25^{\circ}\text{C}$ , the rating shall be reduced according to the actual environmental conditions.
2. Pulse time  $5\mu\text{s}$ , and the pulse width is limited to the maximum junction temperature.
3. Pulse test: Pulse width  $\leq 300\mu\text{s}$ , duty cycle  $\leq 2\%$ .
4. Essentially independent of operating temperature.

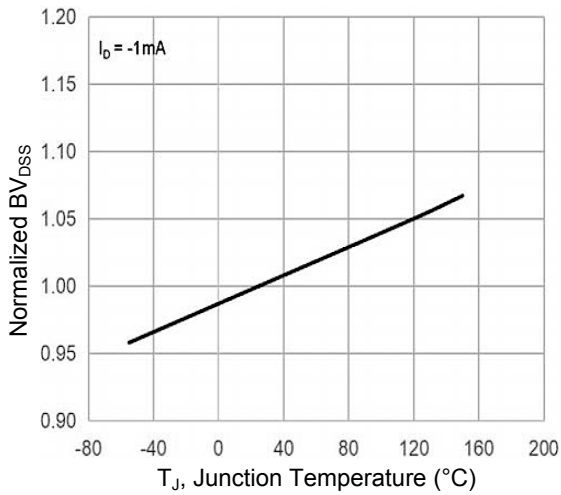
**Typical Electrical and Thermal Characteristic Curves**



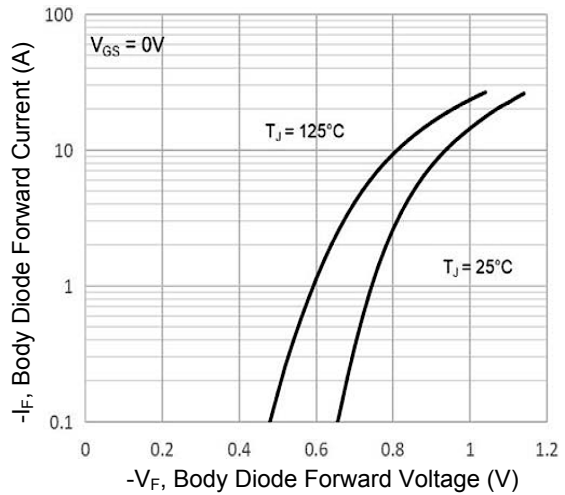
**Figure 1. Output Characteristics**



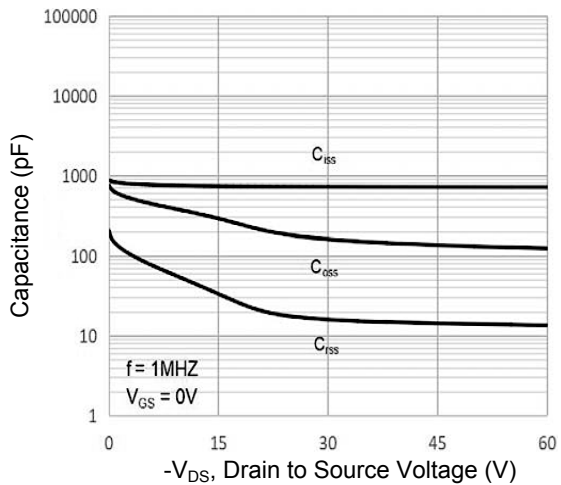
**Figure 2. Transfer Characteristics**



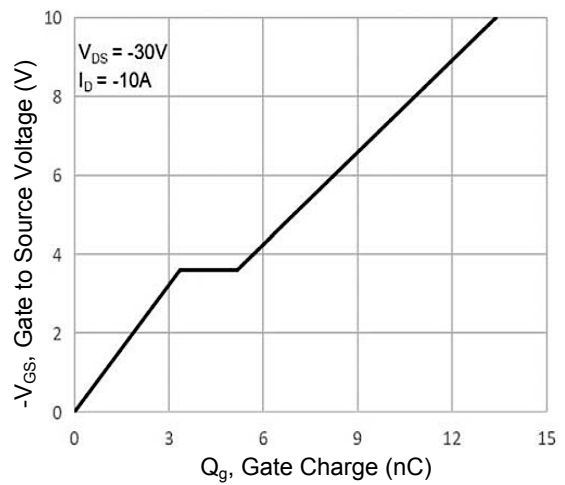
**Figure 3. Normalized  $BV_{DS}$  vs.  $T_J$**



**Figure 4. Body Diode Characteristics**

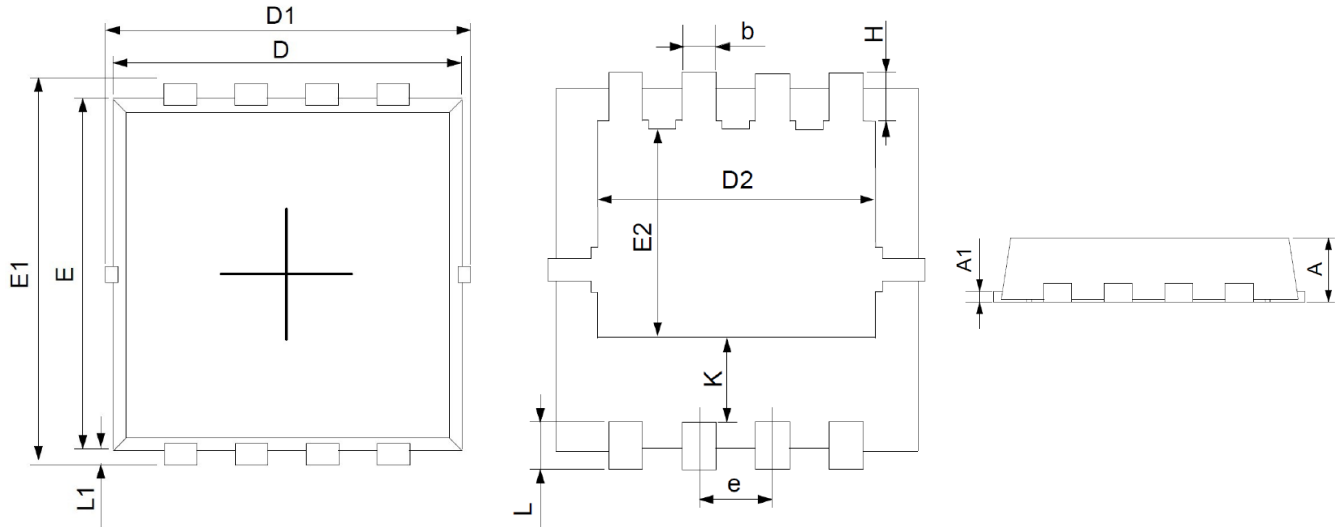


**Figure 5. Capacitance Characteristics**



**Figure 6. Gate Charge Characteristics**

**Package Outline Dimensions (PPAK3x3)**



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.70	0.90	0.028	0.035
A1	0.14	0.20	0.006	0.008
D	3.05	3.25	0.120	0.128
E	2.90	3.10	0.114	0.122
D1	3.10	3.50	0.122	0.138
D2	2.35	2.50	0.093	0.098
E1	3.10	3.50	0.122	0.138
E2	1.64	1.84	0.065	0.072
b	0.25	0.35	0.010	0.014
K	0.59	0.79	0.023	0.031
e	0.55	0.75	0.022	0.030
L	0.25	0.55	0.010	0.022
L1	0.10	0.20	0.004	0.008
H	0.32	0.52	0.013	0.020

**Order Information**

Device	Package	Marking	Packaging	SPQ
GSFN6049	PPAK3x3	N6049	Tape & Reel	5,000 Pcs / Reel